Product End-of-Life Disassembly Instructions

**Marketing Name / Model**
[List multiple models if applicable.]

**Product Category**
Integrated PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

### Items Requiring Selective Treatment
1. Items listed below are classified as requiring selective treatment.
2. Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
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</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>5</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
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<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
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<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
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<tr>
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### Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

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### Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Release 1 screw for HDD cap.
2. Remove HDD cap, remove service stations.
3. Release 4 screws for Stand-ASSY, then remove it.
4. Release 2 screws for ODD-module, then pull ODD-module out of system.
5. Release 4 screws for Rear cover, then remove it.
6. Pull out B-CAS cable and release 1 screw for HDD, then remove HDD module.
7. Release 2 screws for B-CAS, then remove B-CAS module.
8. Remove DIMM module.
9. Release 9 screws for M/B shielding, then remove M/B shielding assy (Figure 1).
10. To remove ram from M/B (Figure 2).
11. Release 2 screws for FAN module, then remove it.
12. Release 9 screws for Thermal module, then remove it.
13. Release 4 screws for TV & WLAN module, then remove them.
14. Release 4 screws for TV set & inverter, then remove them & cables.
15. Release 2 screws for webcam module, then remove it & it’s cable.
16. Release 2 screws for USB cable, then remove it.
17. Remove CPU and release 2 screws for HDD cable, then remove it.
18. Release 2 screws for T/P control board, then remove it & it’s cable (Figure 5).
19. Release 6 screws for side cap sub-assy, then remove them.
20. Release 4 screws for power & ODD & I/O board, then remove them & cables (Figure 4).
21. Release screws for converter board, and then remove converter board (Figure 3).
22. Remove LCD cable.
23. Release 7 screws for middle frame, then remove it.
24. Release 4 screws for TSP module, then remove it.
25. Release 4 screws for LCD bracket, then remove it (Figure 6).
26. 3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective

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25. Release 4 screws for LCD bracket, then remove it (Figure 6).
26.
1. Motherboard
2. Ram x2
3. Converter board
4. I/O board
5. T/P control board
6. LCD panel disassembly process
   a. Remove 3 pcs screws and the pcb cover film from the module.
   b. Release the hooks around the module for remove the front metal frame
   c. Take off panel assembly.
d. Release lamp wire from housing and remove tape.

e. Remove plastic hosing.

f. Remove LGP, lamps (marked in red) and films.